

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**  
**– PATENT APPLICATION –**

Applicant: : Aron T. Lunde  
Application No.: : 10/053,963  
Filed: : January 22, 2002  
Title: : A DIE ASSEMBLY AND METHOD FOR FORMING A  
DIE ON A WAFER  
Examiner : Nguyen, Khiem D.  
Group Art Unit : 2823  
Confirmation No. : 5214  
Attorney Docket No. : 37829.0400

**RESPONSE AND AMENDMENT TO OFFICE ACTION**

Mail Stop AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Applicant hereby responds to the Office Action dated April 13, 2006 and respectfully requests the Examiner to consider the following amendments and remarks:

**Amendments to the Claims** are reflected in the listing of claims, which begin on page 2 of this paper.

**Remarks/Arguments** begin on page 8 of this paper.

**Conclusion** begins on page 14 of this paper.